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Packaging Manufacturers""; ""3. Highly Accelerated Stress Test (HAST)""; ""III. MISCONCEPTIONS IN COMMON RELIABILITY ASSESSMENTOF INTEGRATED CIRCUITS""; ""1. Zero Failure Represents Good Reliability""; ""2. Higher MTTF Represents Better Reliability""; ""3. MTTF Is the Mean Failure Time""; ""4. Exponential Distribution Is Sufficient to Analyze the Test Data""
""5. The Higher the Stress, the More Effective Is the Reliability Test""""""A. Masked Failure Mechanism""; ""B. Variation of Failure Mechanism""; ""6. All Test Data Are Valid""; ""7. Only One Failure Mechanism Exist in the Failed Units""; ""8. Probability Plot Is Sufficient for Test Data Analysis""; ""9. Small Sample Size Is Sufficient""; ""10. The Important of Confidence Interval""; ""IV. CONCLUSION""; ""REFERENCES""; ""DESIGN OF A MULTICHANNEL INTEGRATEDBIOSENSOR CHIP AND MICROELECTRONIC SYSTEMFOR EXTRACELLULAR NEURAL RECORDING""; ""ABSTRACT""; ""1. INTRODUCTION""; ""2. SYSTEM OVERVIEW""
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""3.5. Biasing Circuitry""

Sommario/riassunto

Introduces metamaterials technology, a novel approach for the design of radiofrequency and microwave components and circuits. This book discusses the intrinsic charge transport in organic field-effect transistors based on self-assembled monolayers and on the nature of transport in organic systems.